

"Intelligent SoC Driving the Fourth Industrial Revolution"



ISOCC 2018

15th International SoC Design Conference

November 12-15, 2018
Hotel Inter-Burgo Daegu, Daegu, Korea

✓ About ISOCC

ISOCC has established a long tradition as an annual conference providing the world's premier SoC design forum for leading researchers from academia and industries. ISOCC 2018 welcomes articles in the field of semiconductor circuits and systems dealing with new advanced concept and developments in technology of analog/digital circuits or systems, theory, simulation, modeling, advanced experimental results and experience of SoC with SW, and an emerging technology for the future. ISOCC 2018 is technically co-sponsored by IEEE CAS Society. All accepted papers will be published in the conference proceedings and will be submitted for inclusion in IEEE Xplore. Authors of selected outstanding papers will be invited to submit extended versions of their papers for consideration of publication in the Journal of Semiconductor Technology and Science (JSTS) (www.jsts.org).

✓ Topics of Interest

Topics include, but are not limited to:

- Analog Circuits

- Analog Circuits
- Amplifiers and Filters
- Power Management Circuits

- Data Converters

- Analog-to-Digital Converters
- Digital-to-Analog Converters
- Analog Circuits for Data Converters

- RF/Microwave/Wireless

- RF Circuits and Transceivers
- Microwave and Millimeter-Wave Circuits
- Wireless Communication Circuits

- Wireline

- High-Speed Interface
- Wireline Link

- Digital Architecture and Systems

- Multimedia Systems & Image Processing Applications
- Digital Signal Processing & Communication Systems
- Embedded Software and Systems

- Digital Circuits and Memories

- Digital Integrated Circuits
- Hardware Security
- Nanoelectronics and Gigascale Circuits and Systems
- Memory Circuits & Systems

- SoC Design Methodology

- Software & Algorithm
- Artificial Intelligence and Deep Learning
- HW-SW Co-Design
- Embedded SoC
- SoC Testing
- Design Verification
- FPGA Design
- Signal Integrity / Interconnect Modeling and Simulation

- Circuits and Systems for Emerging Technologies

- Neuromorphic Computing
- Sensory Circuits and Systems
- Biomedical Circuits and Systems
- Automotive Circuits and Systems
- IoT/IoE Circuits and Systems
- 3-D ICs and SoC Packages

✓ International Organizing Committee

General Chair

- **Kwang Hyun Baek** (Chung Ang Univ., Korea)

General Co-Chairs

- **Jun Jin Kong** (Samsung Electronics, Korea)
- **Mohamad Sawan** (Polytechnique Montréal, Canada)
- **Yoshifumi Nishio** (Tokushima Univ., Japan)

Conference Secretary

- **Youngmin Kim** (Kwangwoon Univ., Korea)

✓ Technical Program Committee

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- **Kyung Ki Kim** (Daegu Univ., Korea)

Technical Program Co-Chairs

- **Meng-Fan (Marvin) Chang** (National Tsing Hua Univ., Taiwan)
- **Chip Hong Chang** (Nanyang Technological Univ., Singapore)

Technical Program Vice Chairs

- **Kang-Yoon Lee** (Sungkyunkwan Univ., Korea)
- **Jongsun Park** (Korea Univ., Korea)

"Full Day Tour Around Daegu Area" (free except lunch)

✓ Conference Venue: Hotel Inter-Burgo Daegu

The city of Daegu is surrounded by UNESCO World Heritage Sites (Gyeongju Seokkuram and Bulguksa, Gyeongju Historical Areas, Haeinsa Temple Tripitaka Koreana, and the historic villages of Hahoe and Andong). We are truly glad to host such a prestigious event in the central hub of world heritage sites of Korea.

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<http://www.hotel-interburgo-daegu.com>

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✓ Important Dates

- Submission of Special Session and Tutorial Proposals: **June 22, 2018**
- Notification of Acceptance of Special Session and Tutorial Proposals: **July 9, 2018**
- Submission of Regular Session Full Papers: **July 13, 2018**
- Submission of Special Session Full Papers: **August 17, 2018**
- Notification of Acceptance: **September 10, 2018**
- Submission of Final Papers (for all accepted papers): **September 21, 2018**
- Author & Early-Bird Registration: **September 21, 2018**

✓ Paper Submission

A complete 2-page manuscript must be submitted electronically in PDF format (in Standard IEEE double-column format posted on the conference website). Only electronic submissions will be accepted. For more information, please refer to the conference website (<http://www.isocc2018.org>).



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